

## 7th IEEE **5G++ Summit Dresden**

## Electronics packaging and heterogeneous integration for 5G/6G



Electronics packaging and heterogeneous integration plays a significant role for the development of reliable high-performance systems for 5G/6G applications. Chip package interaction CPI becomes dominant in particular if chip and package is co-designed in a way that passives and matching networks are put outside of the chip for a RF module in order to reduce the system cost with smallest chip size. To improve the reliability and performance of the package, a co-design based on simulations, experiments and material characterization have to be performed. The integration of optics and photonic IC-devices into package are developed for additional improvement of system performance. For Internet of Things applications in order to allow for a natural interaction between human and machine, flexible and stretchable interconnects to connect on-body sensors with transceiver electronics are needed.



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